

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

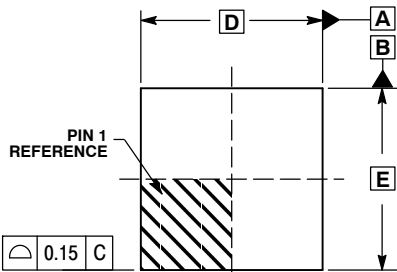
ON Semiconductor®



SCALE 2:1

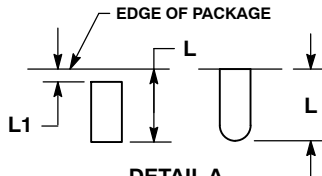
QFN18 3x3, 0.5P
CASE 485BF-01
ISSUE O

DATE 10 FEB 2010

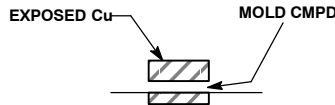


Δ	0.15	C
Δ	0.15	C

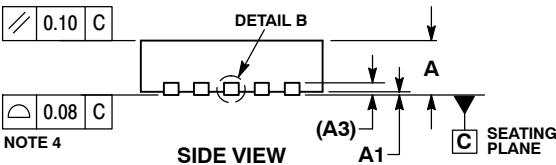
TOP VIEW



DETAIL A
OPTIONAL
CONSTRUCTION

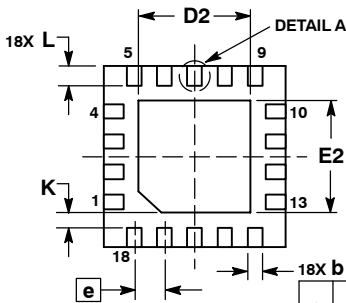


DETAIL B
OPTIONAL
CONSTRUCTION



NOTE 4

SIDE VIEW



BOTTOM VIEW

\oplus	0.10	C	A	B
	0.05	C		

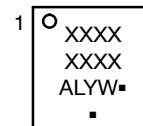
NOTE 3

NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	1.75	1.95
E	3.00	BSC
E2	1.75	1.95
e	0.50	BSC
K	0.20	---
L	0.275	0.375
L1	0.00	0.15

**GENERIC
MARKING DIAGRAM***

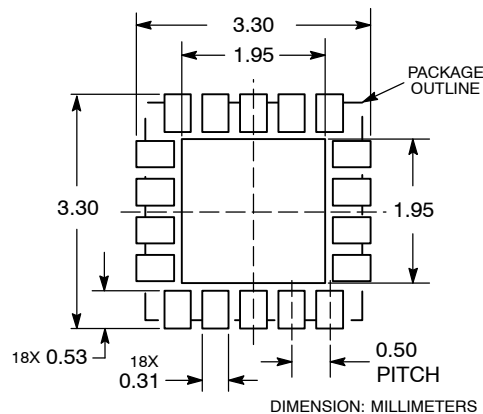


- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED
MOUNTING FOOTPRINT**



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	QFN18 3X3, 0.5P	PAGE 1 OF 2



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